

connected to a pattern of an image chip sensor seated on the flexible PCB by bonding, and the second bump being electrically connected to the circuit of the flexible PCB; epoxy resin ~~for molding~~ molded to a portion of a rear surface of the flexible PCB, on which an image chip is mounted; and a molded material filled up with the epoxy resin to a glass surface between the first bump and the second bump for maintaining air-tightness.

Please amend the specification, beginning at ~~page 3:~~ ^{pg 10 line 5}

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8/3/06

[0060] FIGS. 3 and 4 are a top plan view and a cross-sectional view of an F-COG (flexible PCB chip on glass) CMOS image sensor module illustrating a construction thereof according to the present invention. As shown in FIGS. 3 and 4, the F-COG CMOS image sensor module comprises a flexible PCB 16 for transferring and transmitting electric signals, an image chip 11 seated in a hollow area formed on a side surface of the flexible PCB 16, a predetermined transparent medium 18 having a printed circuit of a predetermined pattern on an upper surface thereof, a first bump 13 and a second bump 14 formed on the upper surface of the transparent medium 18, the first bump 13 being electrically connected to a pattern of the image chip of an image sensor seated on the flexible PCB 16 by bonding, and the second bump 14 being electrically connected to the circuit of the flexible PCB 16; and epoxy resin 19 ~~epoxy resin for molding~~ molded to a portion of a rear surface of the flexible PCB 16, on which an image chip is mounted.

Please amend the specification, beginning at ~~page 3:~~ ^{pg 13 line 3}

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8/3/06

[0074] FIGS. 16 and 17 are a top plan view and a cross sectional view of a COG CMOS image sensor module illustrating a construction thereof according to the present invention. The COG CMOS image sensor module comprises a PCB 26 for transferring and transmitting electric signals, an image chip 21 seated in a hollow area formed on a side surface of the PCB 26, a predetermined transparent medium 28 having a printed circuit 25 of a predetermined pattern on an upper surface thereof, a first bump 23 and a second bump 24 on an upper surface of the transparent medium 28, the first bump 23 being bonded with a pattern of the chip of an image sensor seated on the PCB 26 so as to be electrically connected, and the second bump 24 being bonded with the circuit of the PCB

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AMENDMENTS TO THE SPECIFICATION

Please amend the specification as follows: pg 12 line 21

[0071] As shown in FIG 13, the circuit +4 114 is bonded with the second gold bump 4 by means of ultrasonic wave and heat so as to be electrically connected to each other.

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